# Lasertec receives orders from semiconductor manufacturers for WASAVI BGM300 metrology tools for wafer thinning and advanced packaging applications.

**Shin Yokohama Japan** – Lasertec Corp., a leading supplier of metrology and inspection equipment for advanced semiconductor manufacturing, today announced that it received orders for fully automated production ready WASAVI BGM300 metrology systems from semiconductor manufacturers. The WASAVI (**WA**fer **S**urface **A**nalyzing and **VI**sualization System) BGM300 utilizes Lasertec proprietary interferometry and IR optics to make many critical measurements necessary in the processing of wafers used in 3DIC with Through Silicon Vias (TSV). Leveraging the BGM300's technology enables users to precisely process (grind/CMP) wafers containing the smallest diameter TSV being used in production and R&D today.

3DIC with TSVs was introduced to combat the threat of traditional 2DIC fabrication methods not being able to continue scaling and meeting industry cost and performance requirements. The growing need to reduce package size, reduce device power consumption, and continue down the path of Moore's Law has brought forth the need for even thinner wafers in 3DIC with TSV. The BGM300's ability to quickly and accurately measure ultra-thin remaining Silicon thickness (RST) above TSV diameters down to the industry's most aggressive dimensions is not only enabling the fabrication of these complex fragile semiconductors, but increasing process yield and reliability essential for high-volume manufacturing.

For further information regarding Lasertec's WASAVI BGM300 system, as well a full listing of its leading edge metrology and inspection equipment, please make your way to Booth 710 at the Electronic Components and Technology Conference (ECTC) being held in San Diego CA May 26 ~ 29, 2015 at the Sheraton San Diego Hotel & Marina